



“Optimization Of Material For Ceramics And Electronic Applications By Using Molecular Modeling And Design Of Experiment Methods ”



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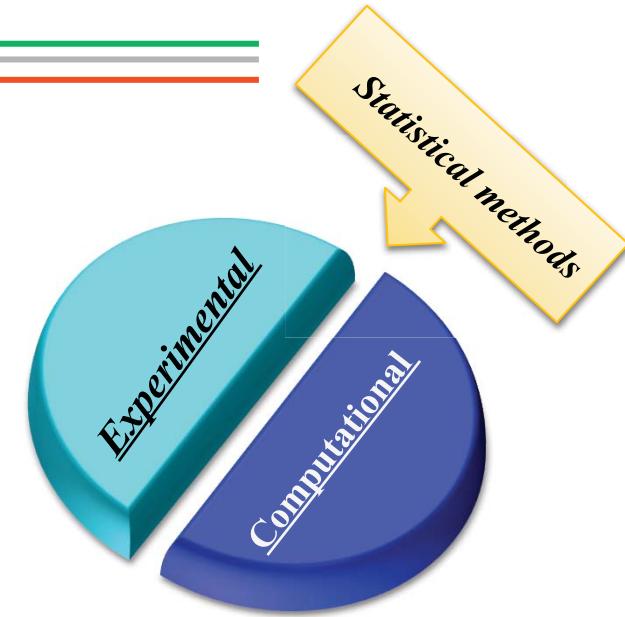


Calatrava's bridge

**Application of DOE
to tiles production
by digital inkjet**



**Modeling of Materials (atomistic – mesoscale)
Statistical Methods (DOE, PLS PCA) applied to Materials Design, Process and Technologies**



**Solid State Battery
• Glass in energy storage**

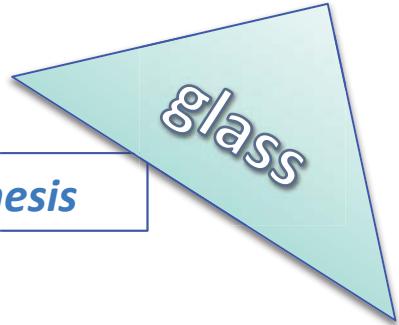


Solid State Battery

- Glass in energy storage**

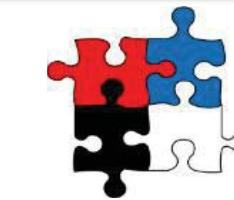
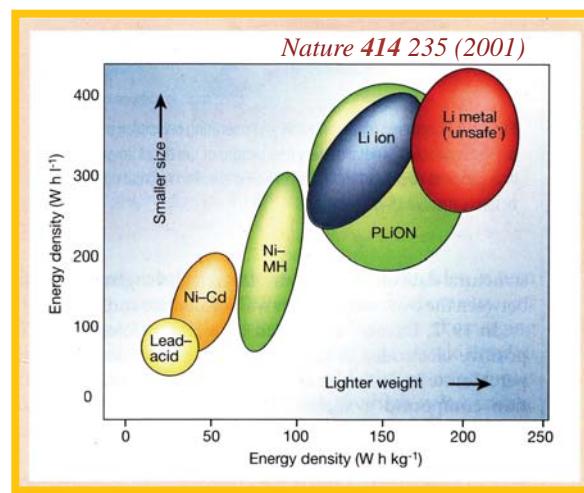
Solid State Batteries

Design



Synthesis

Characterization



Simple fabrication

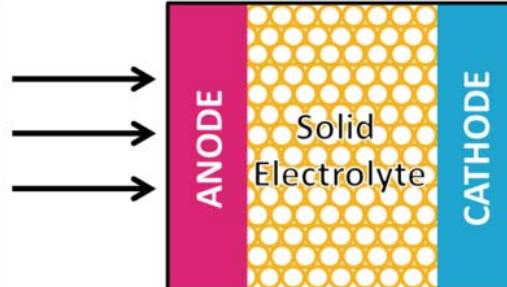
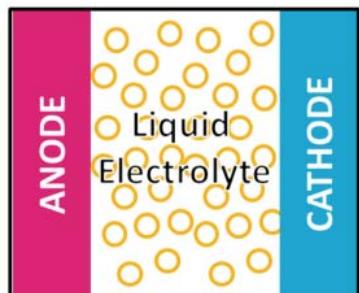


Good safety

High stability



Glass Materials



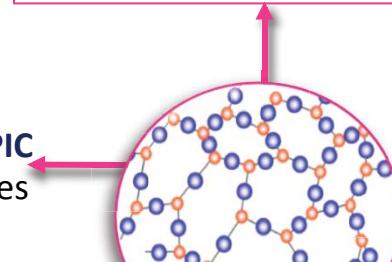
Wide selection of **COMPOSITIONS**

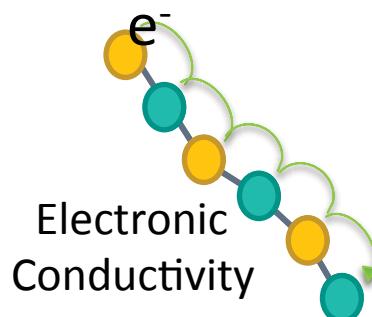
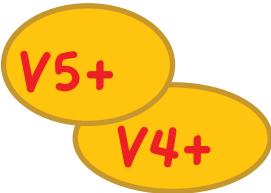
ISOTROPIC properties

Easy **FILM** formation

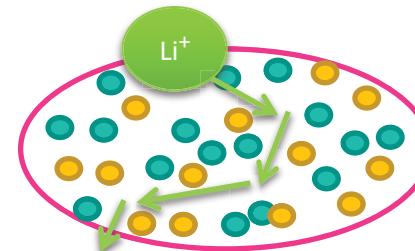
NO grain **BOUNDARIES**

ELECTROLYTE or **CATHODE**

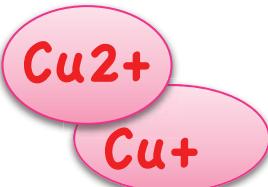




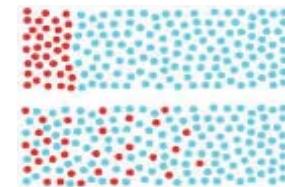
STRUCTURE



Ionic Conductivity



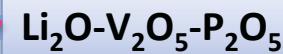
DYNAMICS PROPERTIES



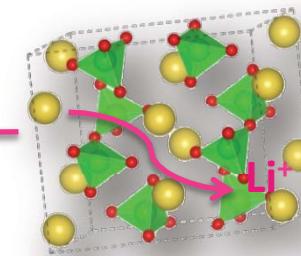
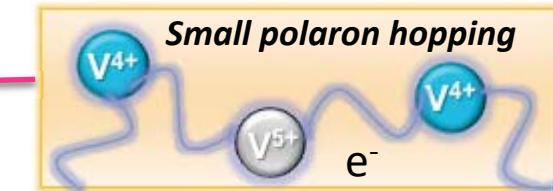
MIXED ELECTRONIC-IONIC CONDUCTIVITY

Outline

MD vs Exp

V Coordination
V-O-V linkages

Cu role

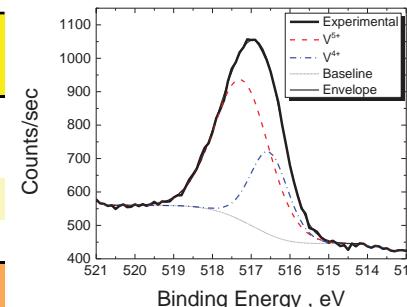


conductivity

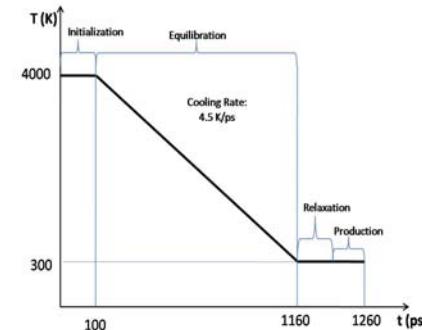
Methods

<i>LiVP</i>	<i>Li₂O</i>	<i>V₂O₅</i>	<i>P₂O₅</i>	<i>V⁴⁺/Vtot</i>	Density (g/cm³)
<i>LiVP10</i>	45	10	45	0.25	2.58
<i>LiVP30</i>	10	30	60	0.4	2.64
<i>LiVP33</i>	33	33	33	0.26	2.66
<i>LiVP50</i>	10	50	40	0.31	2.78
<i>CG</i>	<i>Li₂O</i>	<i>Cu₂O</i>	<i>P₂O₅</i>	<i>Cu²⁺/Cutot</i>	Density (g/cm³)
<i>CG5</i>	45	5	50	0.72	2.49
<i>CG10</i>	40	10	50	0.84	2.51
<i>CG15</i>	35	15	50	0.8	2.69
<i>CG20</i>	30	20	50	0.82	2.88

G. Broglia, C. Mugoni, J. Du, C. Siligardi, M. Montorsi" *J. Non Cryst. Solids.*, , 403, 53-61, 2014
doi: 10.1016/j.jnoncrysol.2014.07.003



XPS analysis

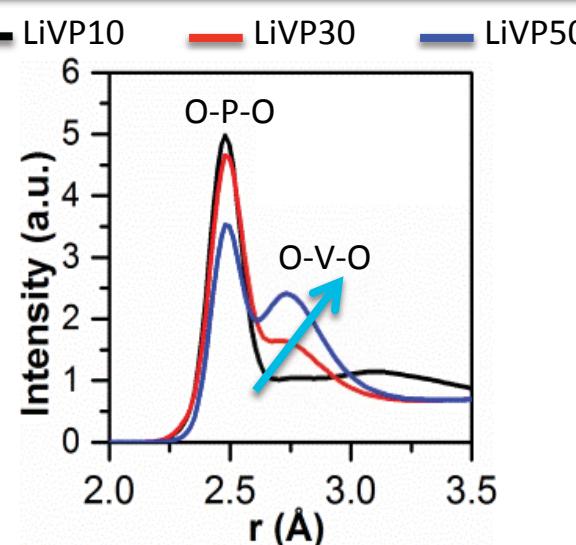


MD
CONVENTIONAL MELT-QUENCH PROCEDURE

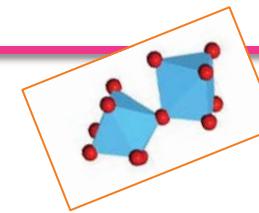
PDF e BAD (short range order)

	<i>V⁴⁺-O</i>	<i>V⁵⁺-O</i>
<i>LiVP10</i>	1.85	1.92
<i>LiVP30</i>	1.79	1.9
<i>LiVP33</i>	1.74	1.78
<i>LiVP50</i>	1.74	1.81
Ref	1.79 ^c	1.79 ^c
	1.53-1.97 ^d	1.53-1.97 ^d

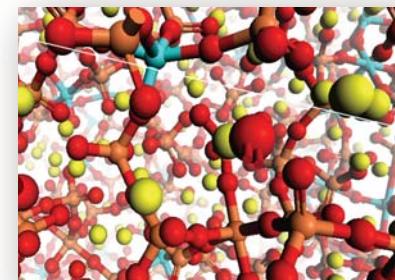
Errors within ±0.005-0.009



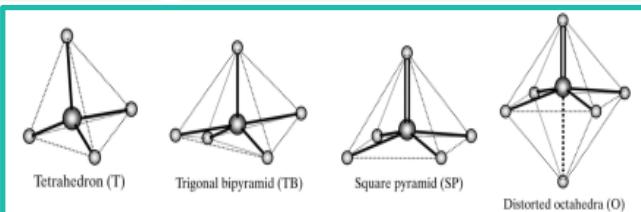
Strong distortion of the V based polyhedra



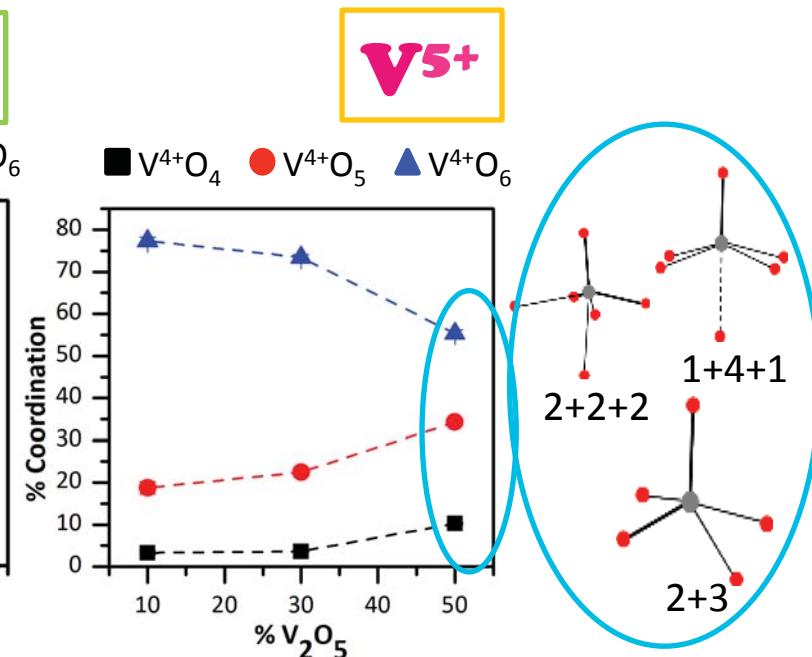
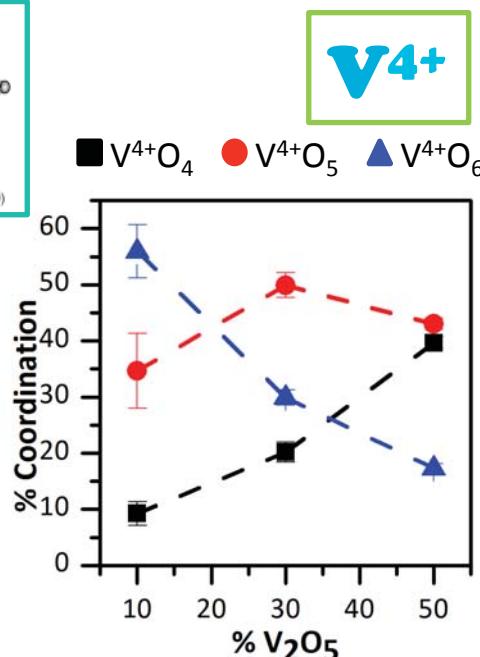
LiVP



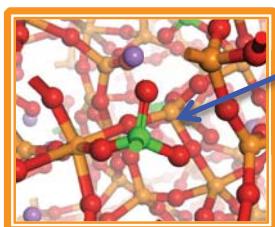
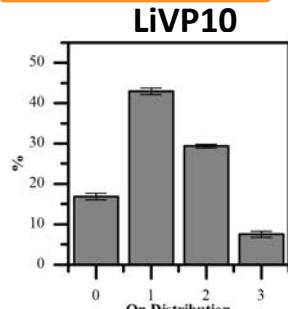
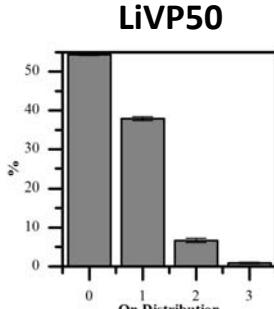
Coordination V



	V^{4+} -O	V^{5+} -O
LiVP10	5.45	5.72
LiVP30	5.10	5.71
LiVP33	5.08	5.68
LiVP50	4.78	5.45

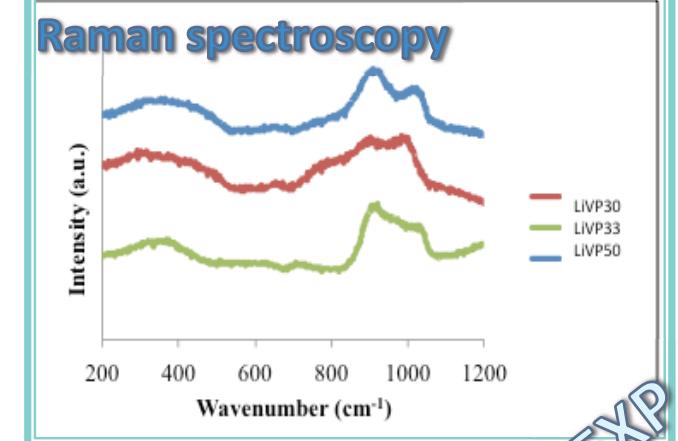


Qn (P) vs Raman (medium range order)

 Q^0  $\%Cu_2O$ 

P Network

V Network



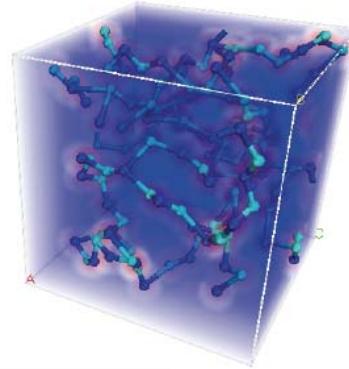
EXP

Linkages

	V^{4+}/V^{tot}	$V^{5+}\text{-O-}V^{4+}$	$P^{5+}\text{-O-P}^{5+}$	$\sigma T_{\text{amb}} \text{ S/cm}$	$\sigma T=180^\circ \text{ S/cm}$	
<i>LiVP10</i>	0.25	0.75	19.81			
<i>LiVP30</i>	0.4	3.9	18.28	2.79×10^{-9}	7.69×10^{-8}	
<i>LiVP33</i>	0.26	6.35	10.2	3.00×10^{-9}	4.30×10^{-6}	
<i>LiVP50</i>	0.31	12.76	4.91	1.70×10^{-8}	1.13×10^{-5}	

✓ Experimental **bulk conductivity increases** when the number of the $V^{5+}\text{-O-}V^{4+}$ linkages(MD) increase

$V^{5+}\text{-O-}V^{4+}$ is independent by the V^{4+}/V^{tot} ratio but is strongly affected by the structural rearrangement taking place for increasing content of V_2O_5 in glass composition.



Mixed electronic-ionic conduction

$33Li_2O\text{-}33V_2O_5\text{-}33P_2O_5$
glass ceramic β -LiVOPO₄

$V^{4+}/V_{\text{tot}} = 0.48$

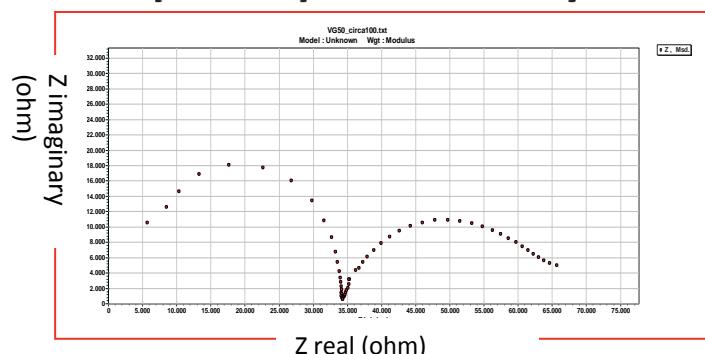
$5 \times 10^{-10} \text{ S/cm}$

$1.7 \times 10^{-7} \text{ S/cm}$

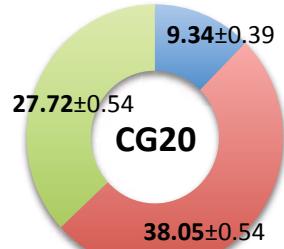
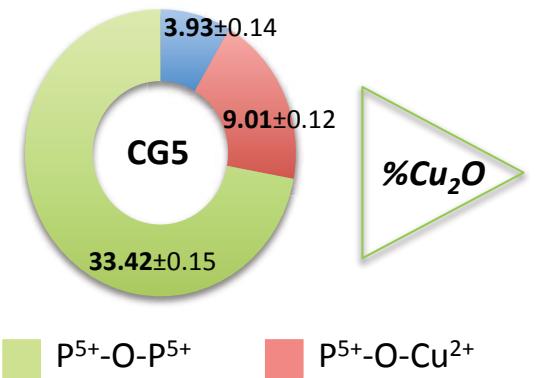
• K. Nagamine, T. Honma, T. Komatsu, J. Am. Ceram. Soc., 2008, 91, (12) 3920.

✓ Conductivity of LiVP33 results **one order magnitude more than the correspondent composition in literature.**

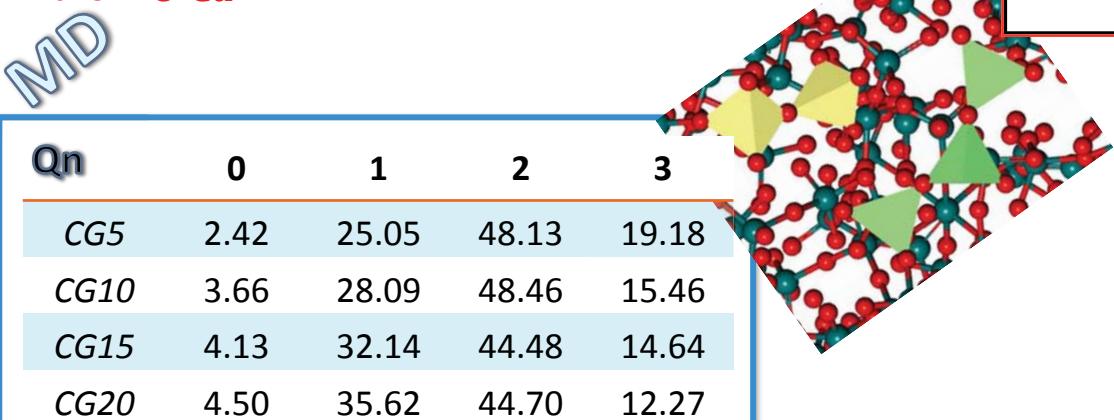
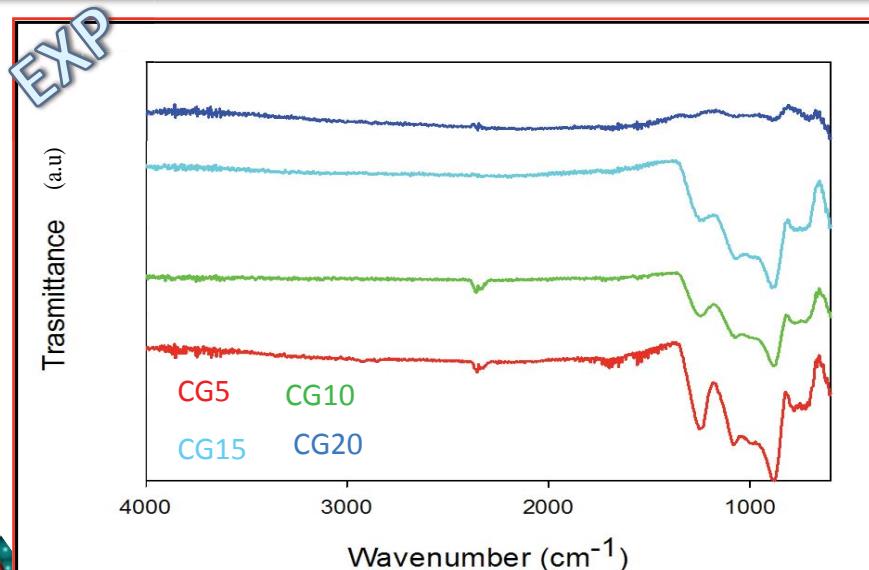
Complex impedance analysis



FTIR vs MD



- P-O-Cu linkages at the expenses of the P-O-P
- The main contribution in P-O-Cu derives from the P-O-Cu²⁺



✓ Slight depolymerization dependent of the Cu₂O content.

NBO/NBO+BO				
	CG5	CG10	CG15	CG20
EXP	0.63	0.63	0.71	0.71
MD	0.66	0.69	0.71	0.72

1088 cm⁻¹

1265 cm⁻¹

890 cm⁻¹

Intensity decreases can be attributed to the existence of P - O - Cu bonds

The decrease of (PO₂)_{as} intensity confirms that the (O-P-O⁻...Li⁺) bonds are substituted by P-O-Cu bonds when Li₂O is replaced by Cu₂O.

The intensity decreases could be associated to a depolymerization of phosphate chains.

CONDUCTIVITY MEASUREMENTS

Two possible conduction mechanism

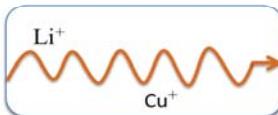
Electron hopping

From Cu⁺ to Cu²⁺

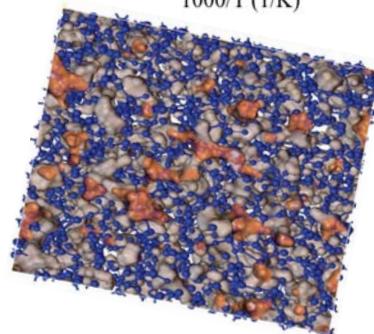
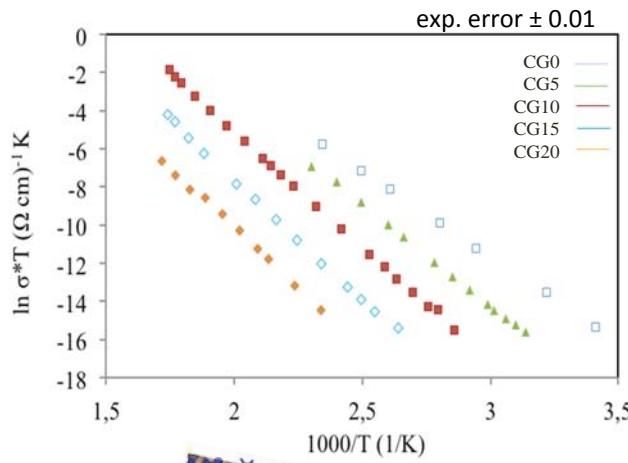


Ionic conductivity

Li⁺ and Cu⁺ migration



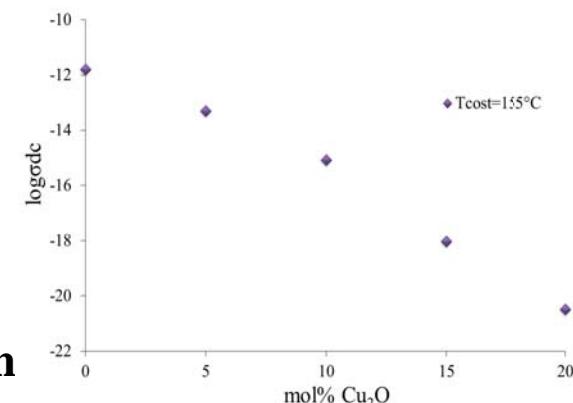
$$\text{Arrhenius equation } \sigma T = \sigma_0 \exp(E_{dc}/kT)$$



The conductive value **decreases (2 order of magnitude)** with the increase in copper oxide content

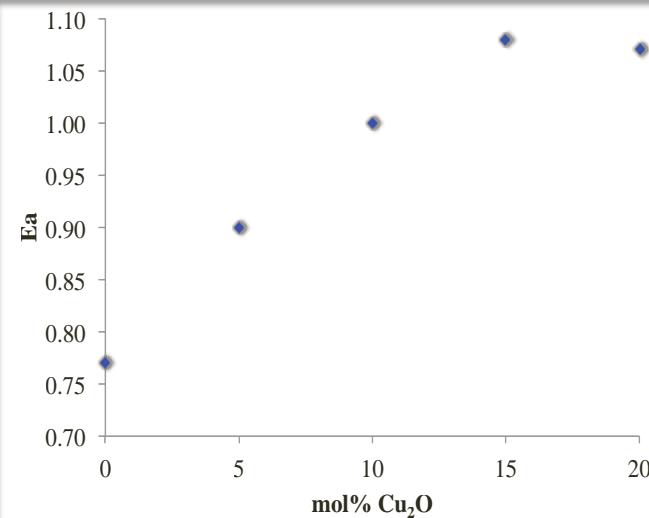
ionic conduction

Conductivity vs Cu₂O mol%



concentration-dependent activation energy

Copper Effect



classic mixed mobile ions effect (MMIE)

- (Ionic conductivity - In agreement with Li-Zn-P2O5 glasses)
- "Crystallization Process and Mixed Alkali Effect in Lithium-Potassium Borate Glass"

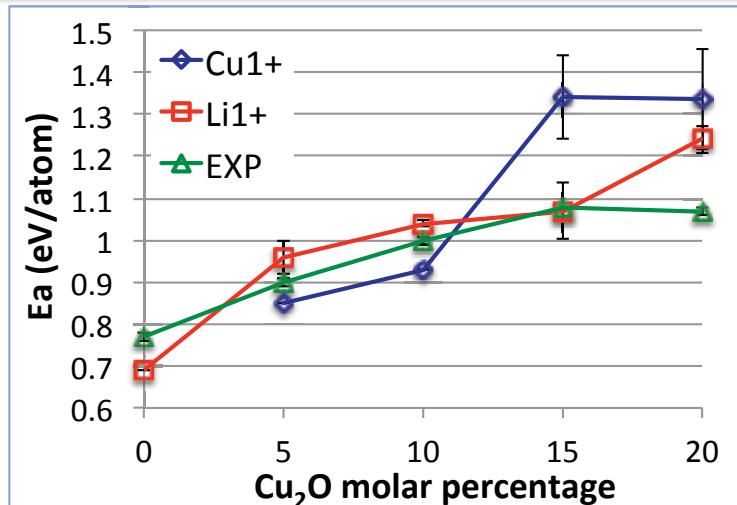
DIFFUSION ANALYSIS

Mobile ion

Only Cu⁺

Only Li⁺

Li⁺ + Cu⁺



Ionic conductivity due to the Li⁺ diffusion in glass structure

MD

CG5 CG10 CG15 CG20

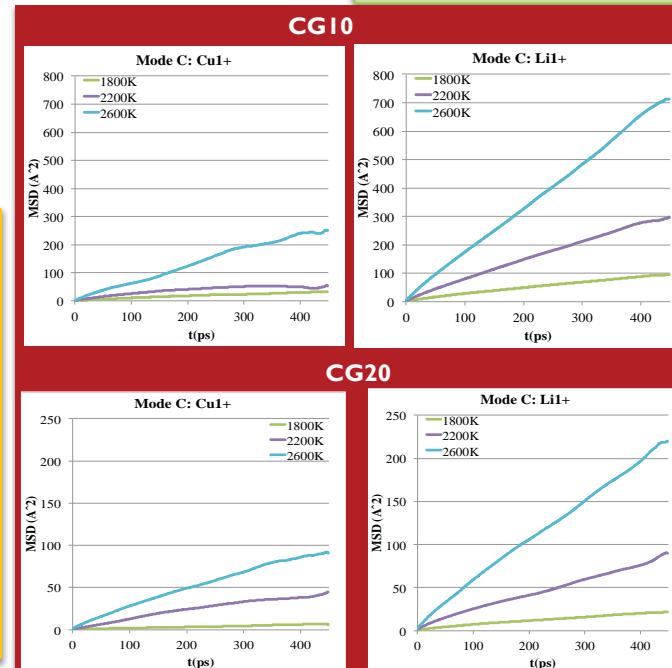
$Cu^{1+}-O-Cu^{2+}$ 0.22 ± 0.03 0.49 ± 0.09 1.66 ± 0.07 2.00 ± 0.58

The diffusion of Li⁺ promotes the diffusion of Cu⁺ in the glass network

The diffusion of Li⁺ ions is higher than Cu⁺ in all glasses

The increase of Cu₂O content leads to a decrease of both Cu⁺ and Li⁺ motion.

MMIE



The amount of Cu^{1+-O-Cu²⁺ remains too small to create conductive path in the systems,}

NO ELECTRONIC CONTRIBUTION

Conclusion

- From P_2O_5 network to V_2O_5 network

Increase of
 V_2O_5
content

Increase of
 V_2O_5 / P_2O_5
ratio

LiVP



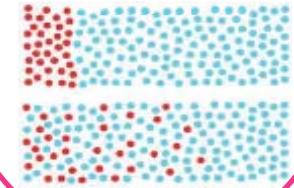
Increased
electronic
contribution

- Linear increase of V-O-V linkages

presence of
P-O \cdots Cu
bonds

Ionic
conductivity:
Lithium
diffusion
with a MMIE

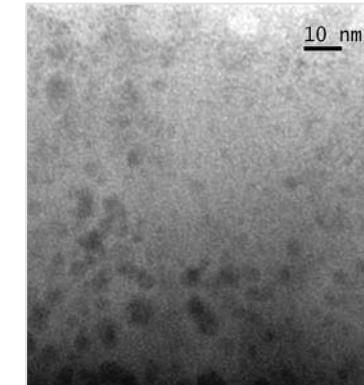
CG



Work in progress

$Cu_2O \cdot V_2O_5 \cdot Te_2O_3$

$10^{-5} S/cm$
 T_{room}



Cu^0 nanoparticles in
glass matrix

Work in progress

Application of DOE to design and production of ceramic tiles

Multivariate Statistical Methods

GET MAXIMUM AMOUNT OF INFORMATION PERFORMING A MINIMUM SET OF EXPERIMENTS

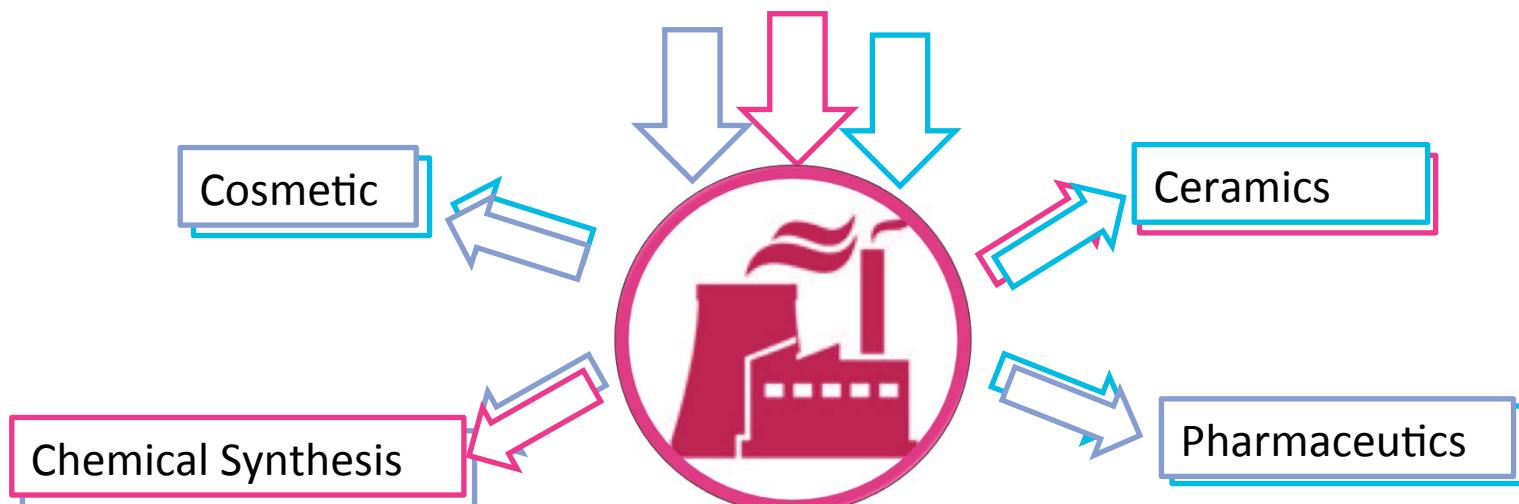
DESIGN OF EXPERIMENTS
DOE

PRINCIPAL COMPONENT ANALYSIS
PCA

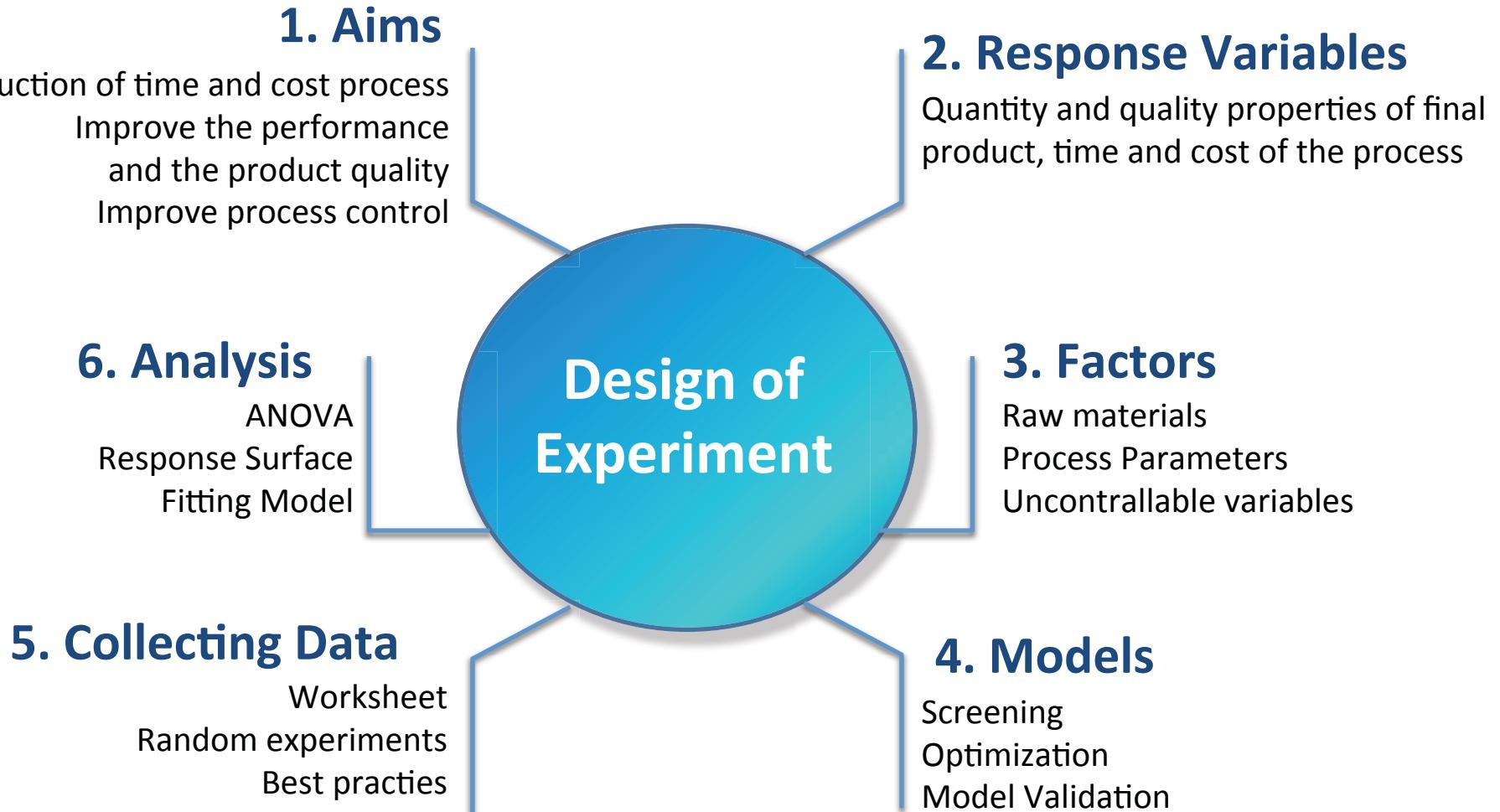
EXTRACTING MAXIMUM AMOUNT OF INFORMATION FROM COMPLEX DATA SET

RELATE THE INFORMATION TO DESCRIBE THE OBSERVED DATA AND TO MAKE REASONABLE PREDTICIONS FOR NEW OBSERVATIONS

PARTIAL LEAST SQUARE
PLS



Design of Experiment



Case Study

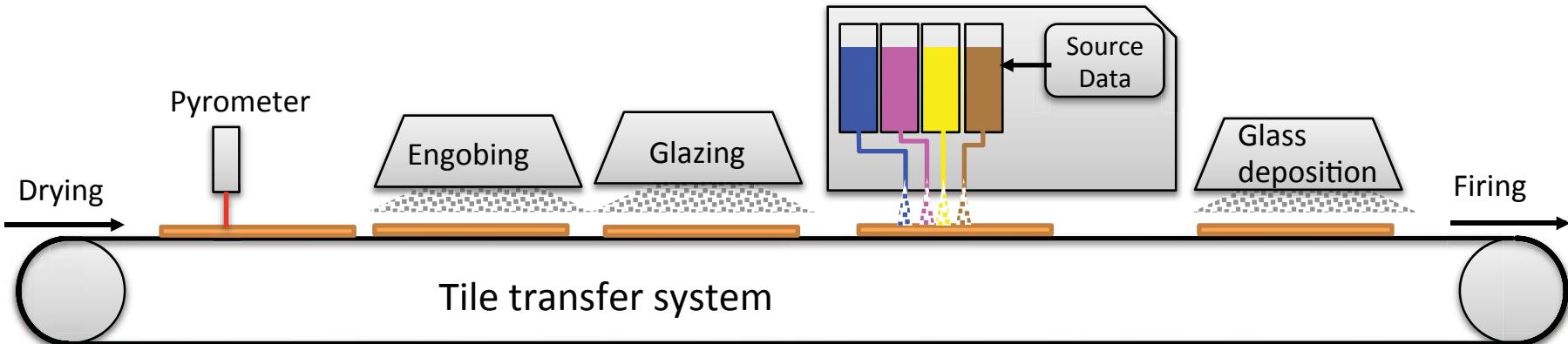
Improve Quality



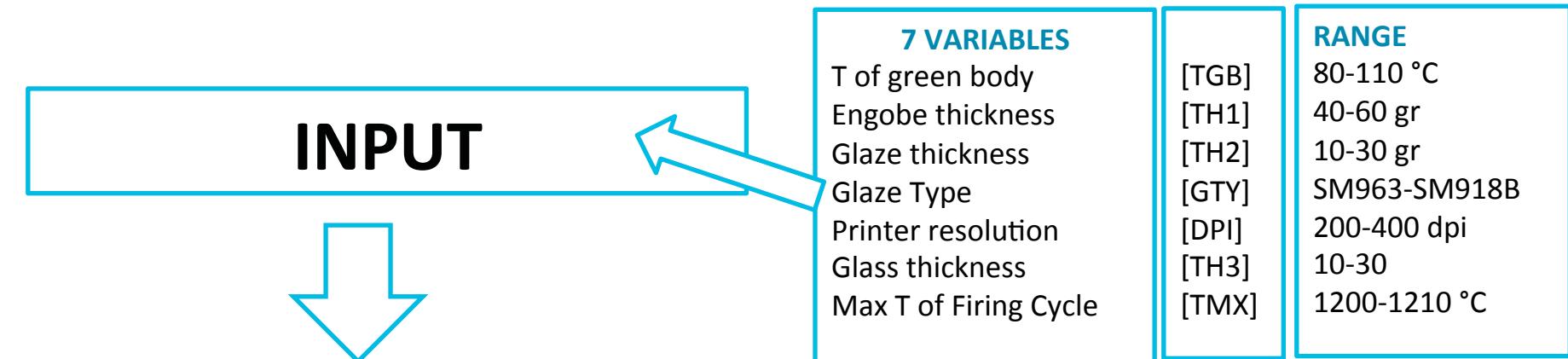
Improve Control



Tile Manufacturing & Digital Ink-jet printing



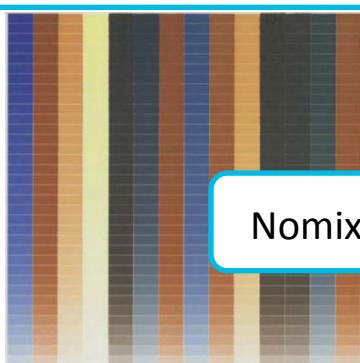
PROCESS MAP



IN-LINE TILE PRODUCTION

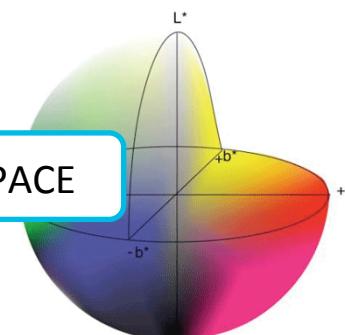


RESPONSES



Nomix- Target tile

CIELab SPACE

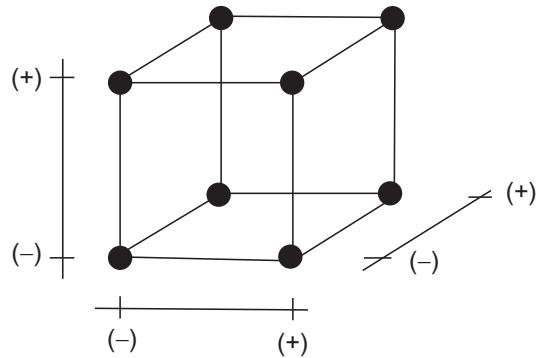


PANEL TEST

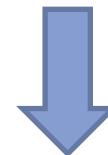


DOE APPROACH

Experimental Domain



FULL
factorial 2^K



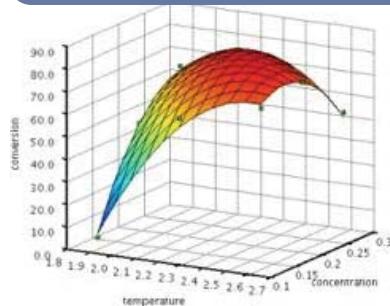
FRACTIONAL
factorial 2^{K-P}

128
TESTs

SCREENING
DESIGN

30
TESTs

Model



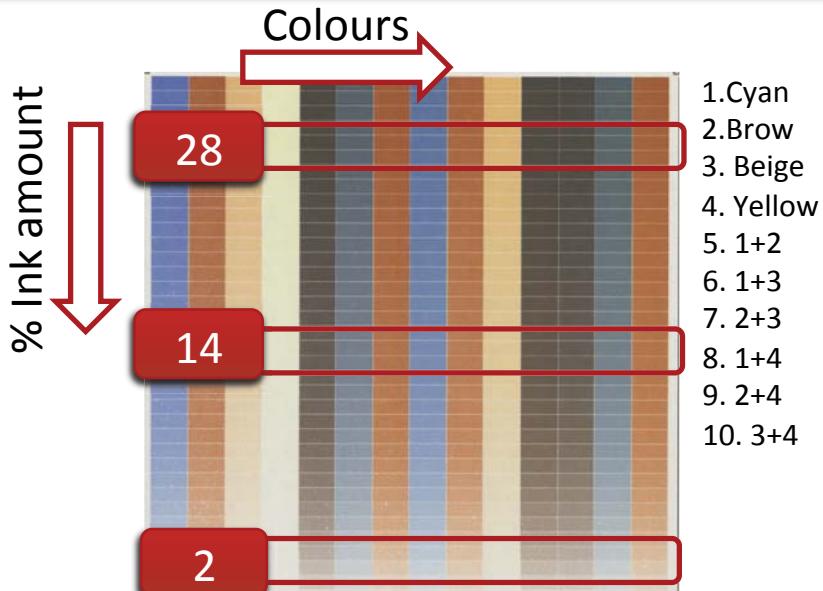
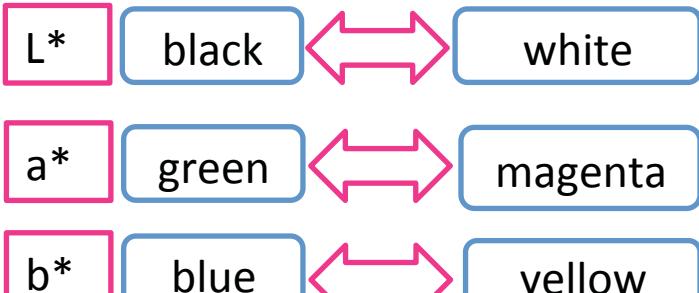
Linear Model

$$y = \beta_0 + x_1 \beta_1 + x_2 \beta_2 + \dots + x_n \beta_n + x_{1,2} \beta_{1,2} + x_{1,3} \beta_{1,3} + \dots + \varepsilon$$

Response Variables

CIELab SPACE

GOAL: HOW TO CONTROL THE COLOR QUALITY



PANEL TEST

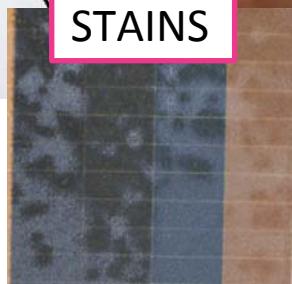
GOAL: HOW TO PREVENT DEFECT FORMATION



WHITE DOTS



STAINS



ROUGHNESS

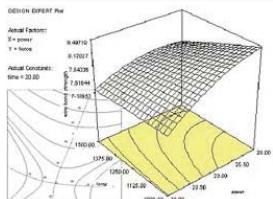


CIELab: MOST INFLUENTIAL VARIABLES

	TGB	TH1	TH2	GTY	DPI	TH3	TMX
L		✓	✓		✓	✓	
a			✓	✓	✓	✓	
b		✓	✓	✓	✓	✓	

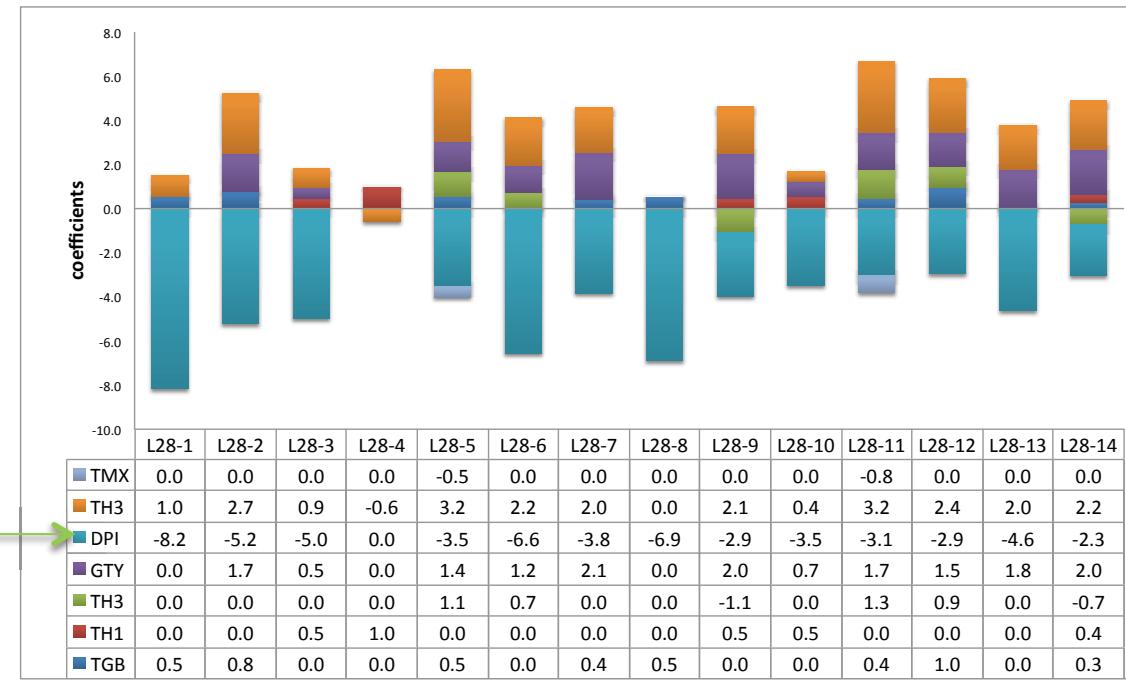
7 VARIABLES	
T of green body	[TGB]
Engobe thickness	[TH1]
Glaze thickness	[TH2]
Glaze type	[GTY]
Printer resolution	[DPI]
Glass thickness	[TH3]
Max T of Firing Cycle	[TMX]

MODELS



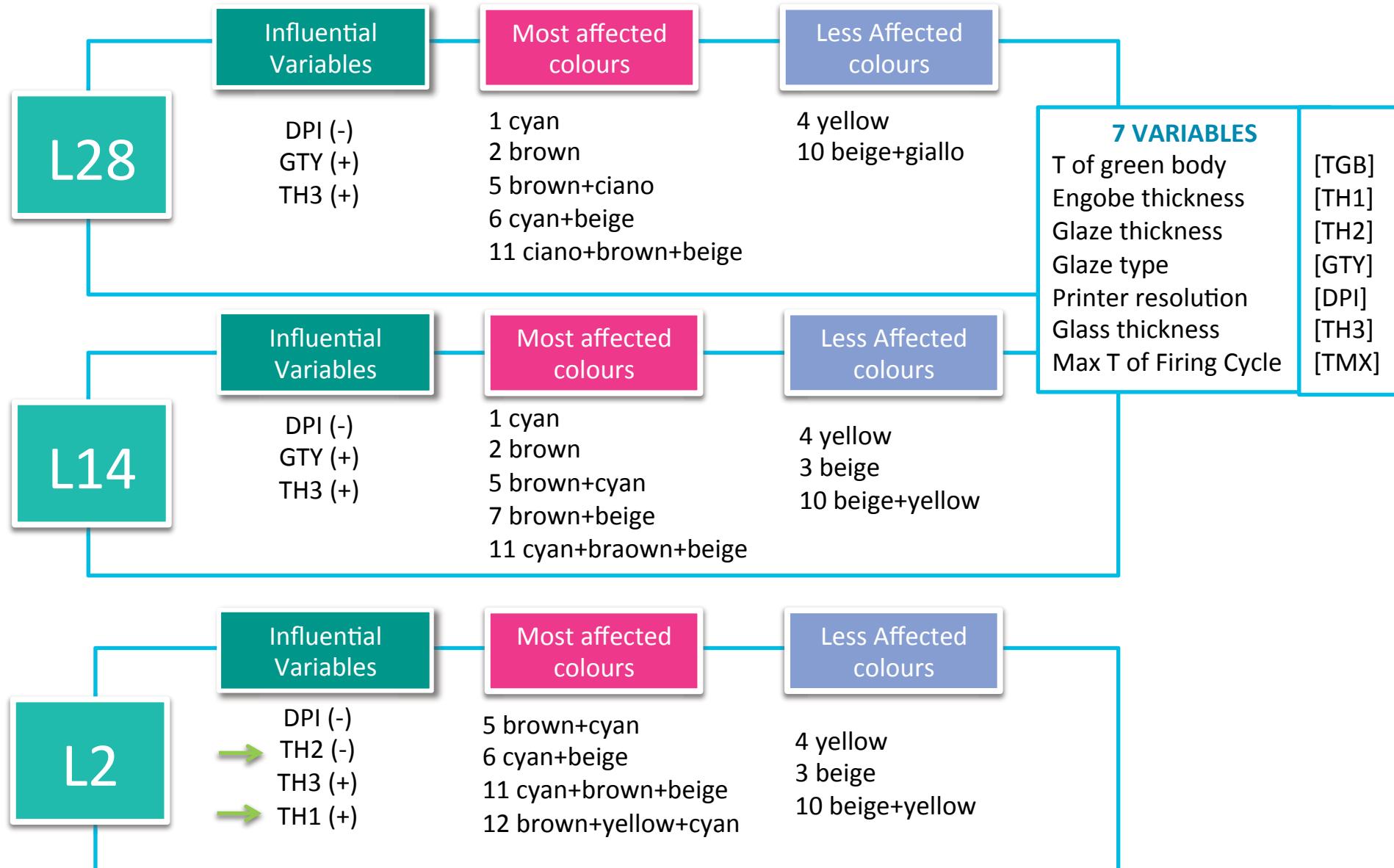
Weights of the variables

coefficients : for L28 the printer resolution (dpi) increasing lead to the luminosity decrease.



$$y = \beta_0 + x_1 \beta_1 + x_2 \beta_2 + \dots + x_n \beta_n + x_{1,2} \beta_{1,2} + x_{1,3} \beta_{1,3} + \dots + \varepsilon$$

CIELab: MOST INFLUENTIAL VARIABLES



DEFECT: MOST INFLUENTIAL VARIABLES

	TGB	TH1	TH2	GTY	DPI	TH3	TMX
White Dots	✓		✓		✓	✓	
Stains				✓	✓	✓	
Roughness			✓	✓	✓	✓	

7 VARIABLES

T of green body
Engobe thickness
Glaze thickness
Glaze type
Printer resolution
Glass thickness
Max T of Firing Cycle

[TGB]
[TH1]
[TH2]
[GTY]
[DPI]
[TH3]
[TMX]

BEST OPERATING CONDITION

WHITE DOTS

T of green body..... 80
Glaze thickness..... 30
Printer resolution..... 400
Glass thickness..... 10

STAINS

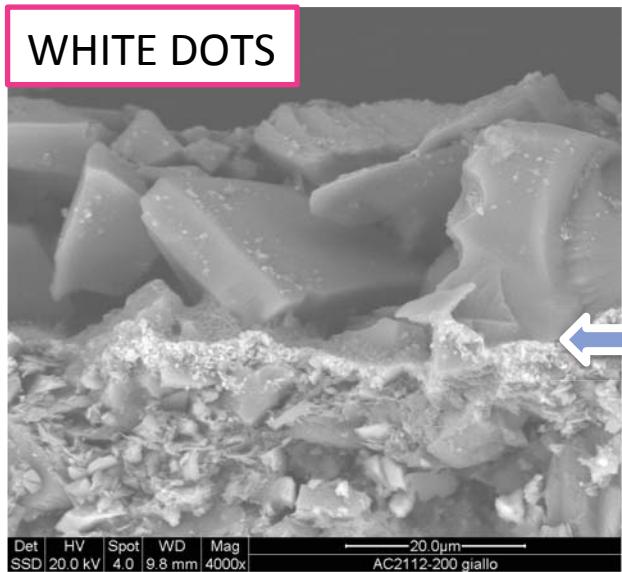
Glaze type..... SM693
Printer resolution..... 200
Glass thickness..... 10

ROUGHNESS

Glaze thickness..... 30
Glaze type..... SM693
Printer resolution..... 200
Glass thickness..... 10

CAUSE-EFFECT RELATIONS

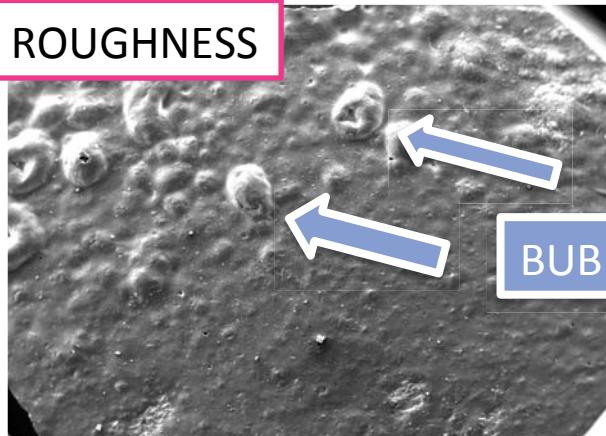
WHITE DOTS



Glassy:
Glass fraction

Ink
Glassy:
Clay fraction

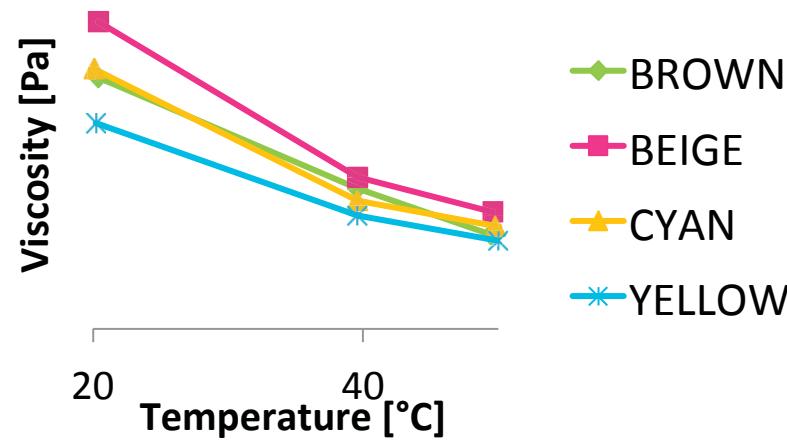
ROUGHNESS



BUBBLES FORMATION DUE TO
THE NOT SUITABLE VISCOSITY
OF SM918 GLAZE

	TGB	TH1	TH2	GTY	DPI	TH3	TMX
White Dots	✓	✓	✓	✓	✓		
Stains			✓	✓	✓		
Roughness	✓	✓	✓	✓	✓		

Ink viscosity Vs Temperature



Work in Progress

STAINS FORMATION DUE TO
THE NOT SUITABLE SURFACE
TENSION OF SM918 GLAZE

STAINS